5.2 Vishay Sfernice France

Contact Information

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|--|--------------------------------|--|
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Initial Qualification

| Qualification Certificate No. | Validity Dates | Type Designation |
|-------------------------------|-----------------------|---|
| 287 | Feb. 2009 - Feb. 2011 | Thin Film Technology for Chip, Wraparound, Single and Network Resistors, Fixed, Based on Types P for Single Chip, PRA and CNW for Resistor Networks |

Maintenance of Qualification

| Qualification Certificate No. | Validity Dates | Comment |
|----------------------------------|----------------------|--|
| 287A | Feb, 2009- Feb. 2011 | CNES application No. 287A and DCR 528. |
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| | | |
| | | |
| | | |

Applicable Documents

ESCC Generic Specification No. 4001

ESCC Detail Specifications No. 4001/023, 4001/025

Vishay Process Identification Document PID PID-TFD P PRA CNW

List of Qualified Components

| Variant No. By Form | Component Type | ESCC Detail |
|-----------------------|--------------------------------|---------------|
| Factor | | Specification |
| 09 | P 0603 FR Failure Rate Level R | 4001/023 |
| 01 and 05 | P 0603 HR | 4001/023(*) |
| 10 | P 0805 FR Failure Rate Level R | 4001/023 |
| 02 and 06 | P 0805 HR | 4001/023(*) |
| 11 | P 1206 FR Failure Rate Level R | 4001/023 |
| 03 and 07 | P 1206 HR | 4001/023(*) |
| 12 | P 2010 FR Failure Rate Level R | 4001/023 |
| 04 and 08 | P 2010 HR | 4001/023(*) |
| 01 to 07 and 22 to 28 | PRA 100 HR | 4001/025 |
| 08 to 14 and 29 to 35 | PRA 135 HR | 4001/025 |
| 15 to 21 and 36 to 42 | PRA 182 HR | 4001/025 |

 $^{^{\}star}$ Note that gold finish variants are not intended for de-golding and tinning

Technology Flow Abstract

1. Technology Flow

The thin film technology for chip, fixed, wraparound, single and network resistors are designed on types based on P for single chip, PRA for 2 to 8 resistors of similar value and CNW for 2 to 8 resistors with at least two different values with the same form factor as PRA.

| Technology Flow | Scope | Site |
|-----------------|----------------------------|--------------------------------|
| Design Centre | Single resistor chips in | Vishay S.A. |
| | 0605, 0805, 1206 and 2010 | Division Résistances de Très |
| | formats | Haute Précision |
| | 2 to 8 resistors of | 199, Boulevard de la Madeleine |
| | similar value in formats | B.P. 1159 |
| | 0603, 0805 and 1206 | 06003 Nice Cedex 1 |
| | 2 to 8 resistors with at | France |
| | least 2 different values | |
| | with the same form factor, | |
| | 0603, 0805 or 1206 | |
| Fabrication | Film deposition | As above |
| | Photolithography | |
| | Thermal treatment | |
| | Passivation | |
| | Thermal stabilization and | |
| | control | |
| Assembly | Laser trim | As above |
| | Protective layer | |
| | Termination and Test | |
| Test | Chart 2, 3 and 4 | As above |
| | Periodic Testing | |

⁽a) Basic Information

The technology consists of:

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- substrate: High purity alumina (99.5%)
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- Resistive Layer: Nickel chromium

Protection: Silicon NitrideTermination: Nickel barrier

- Processes: Thin film deposition

- Finish: SnPbAg or Au

Critical resistance by style:

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- P 0603 FR: 25 kΩ

- P 0603 HR: 12.25 kΩ

- P 0805 FR: 80 kΩ

- P 0805 HR: 45 kΩ

- P 1206 FR: 90 kΩ

- P 1206: 40 kΩ

- P 2010 FR: 80 kΩ

- P 2010 HR: 45 kΩ

- PRA 100: 12.25 kΩ

- PRA 135: 56.25 kΩ

- PRA 182: 100 kΩ
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(b) Component Types

This table presents the available formats as defined in the variants table in the Detail Specifications.

Variants with established reliability in accordance with Basic Specification No. 26000 are designated with an "FR" suffix here for convenience. Variants 09, 10, 11 and 12 have established reliability level "R" at 60% confidence level.

2. Design

The Design Manuals cover the design rules and limits:

- HP-BE/001 (Maîtrise de la conception)
- HP-BE/004 (Données technologiques, Régles d'implementation, Performances)

Critical design characteristics:

- Minimum metal width: 10µm
- Power dissipation lower then 250mW/mm²
- Current density lower than 7000 A/mm²
- Electrical field lower than $5V/\mu m$

3. Fabrication / Assembly

The manufacturing flows and procedures are described in section 4 of Vishay PID.

4. Test

Complete test sequence as detailed in ESCC Generic 4001 and the relevant Detail Specifications is conducted by Vishay Sfernice.

The deletion of the Third Harmonic Control requirement from ESCC Detail Specification No. 4001/023 for thin film wraparound technology is documented in reference report MAT/3HC/07.02 revision 3 dated 2007-06-20

For variants with established reliability the efficiency of the Overload Test is increased with the implementation of a resistance change rejection criteria of 500 ppm and approved by TRB decisions on 2007-04-04

5. Radiation Characteristics

The resistors covered in this technology domain is considered insensitive to radiation effects

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